

ABSTRACT

Insulating layers of a redistribution layer of a semiconductor package may be formed as a polymer film having inorganic fillers formed therein. The inorganic fillers
5 may trap reactive materials to inhibit and/or substantially prevent the metal conductors, such as chip pads of the semiconductor chip being packaged, from being damaged by the reactive material. As a result, the reliability and the durability of the semiconductor package may be improved.

10 Fig. 6A